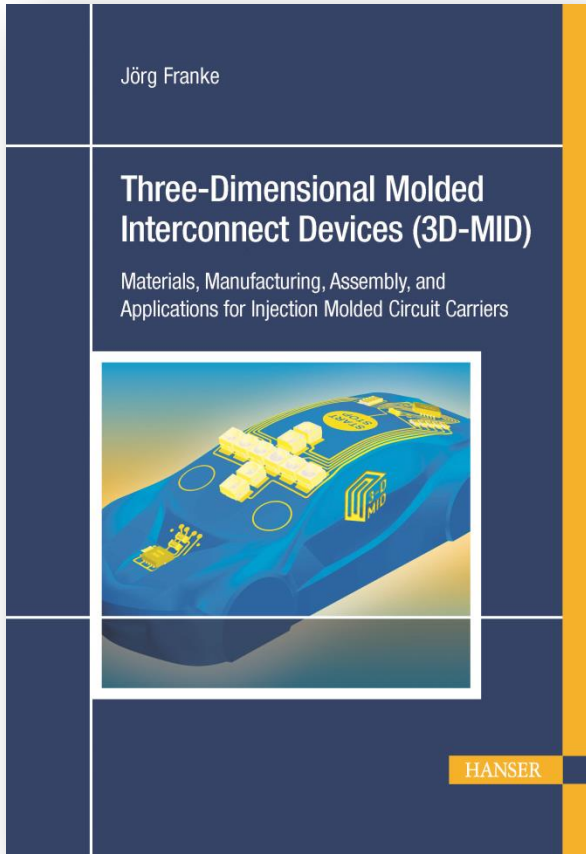




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The editor of this book is **Prof. Dr.-Ing. Jörg Franke**. Professor Franke holds the chair of the Institute for Factory Automation and Production Systems (FAPS) at the Friedrich-Alexander-University Erlangen-Nuremberg. He also chairs the board of the Research Association Molded Interconnect Devices (3-D MID) e.V. and he is director of the E|Drive Center, the Bavarian Technology Center for Electrical Drives. Professor Franke worked in the industry for many years with companies that include McKinsey, Robert Bosch GmbH, ZF Lenksysteme (ZFLS) GmbH, and INA Schaeffler KG. In his most recent industrial capacity he was chairman of the management board of ABM Greiffenberger Antriebstechnik GmbH.